



News Release

SPIIL Shareholders Approved NT\$ 4.6 Dividend, including NT\$ 4.5 Cash Dividend and NT\$ 0.1 Stock Dividend

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Taichung, Taiwan, June 13, 2008 **Siliconware Precision Industries Co., Ltd.** ("SPIL" or "the Company")(Taiwan Stock Exchange:2325.TT, NASDAQ:SPIL) today held a shareholders' meeting, at which the shareholders approved the proposal for distribution 2007 profits.

The major conclusions of this shareholders' meeting are as follows:

1. Shareholders approved the 2007 Business Report. Net sales for 2007 were NT\$ 64,622 million, and net income was NT\$ 17,489 million with diluted EPS of NT\$ 5.77 per share.
2. Shareholders approved a proposal for distribution of 2007 profits:
 - (1) A dividend of NT\$ 4.6 per share will be distributed to the common shareholders, including a cash dividend of NT\$ 4.5 per share and a stock dividend of NT\$ 0.1 per share.
 - (2) Employees' bonuses will be distributed in both cash and stock, including NT\$ 1,100 million distributed in cash and NT\$ 471 million distributed in stock.
 - (3) After the distribution, SPIL's total outstanding shares will increase by approximately 77.9 million shares.
3. Shareholders approved to elect 9 Directors and 3 Supervisors. The 9 Directors elected are Bough Lin, Chi-Wen Tsai, Wen-Lung Lin, Yen-Chun Chang, Wen-Jung Lin, Hsiu-Li Liu, Ing-Dar Liu, Jing-Shan Aur, Jerome Tsai (Representative of Pei-Sheng Cultural Educational Foundation). The 3 Supervisors elected are Wen-Lung Cheng, Fu-Mei Tang, Teresa Wang (Representative of Siliconware Investment Company).



About SPIL

Siliconware Precision Industries Ltd. ("SPIL")(NASDAQ:SPIL, TSE:2325) is a leading provider of comprehensive semiconductor assembly and test services. SPIL is dedicated to meeting all of its customers' integrated circuit packaging and testing requirements, with turnkey solutions that range from design consultations, modeling and simulations, wafer bumping, wafer probe and sort, package assembly, final test, burn-in, to drop ship. Products include advanced leadframe and substrate packages, which are widely used in personal computers, communications, Internet appliances, cellular phones, digital cameras, cable modems, personal digital assistants and LCD monitors. SPIL supplies services and support to fabless design houses, integrated device manufacturers and wafer foundries globally. For further information, visit SPIL's web site at www.spil.com.tw.

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